



# T2550H-600T

SNUBBERLESS™ HIGH TEMPERATURE

25A TRIACs

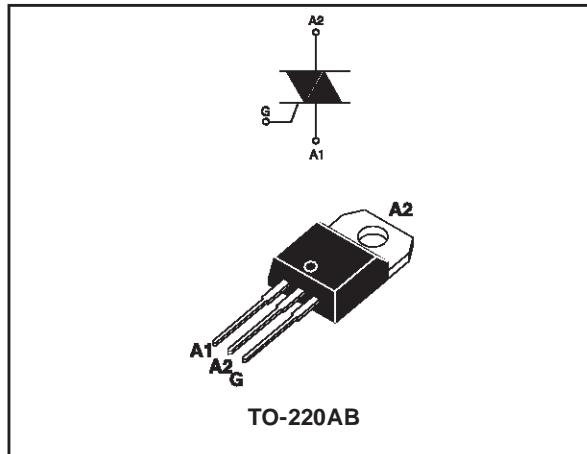
## MAIN FEATURES:

Symbol	Value	Unit
$I_T(\text{RMS})$	25	A
$V_{\text{DRM}}/V_{\text{RRM}}$	600	V
$I_{\text{GT}}(Q_1)$	50	mA

## DESCRIPTION

Specifically designed for use in high temperature environment (found in hot appliances such as cookers, ovens, hobs, electric heaters, coffee machines...), the new 25 Amps T25500H triacs provide an enhanced performance in terms of power loss and thermal dissipation. This allows optimization of the heatsinking dimensioning, leading to space and cost effectiveness when compared to electro-mechanical solutions.

Based on ST snubberless technology, they offer high commutation switching capabilities and high noise immunity levels. And, thanks to their clip assembly technique, they provide a superior performance in surge current handling.



## ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter			Value	Unit
$I_T(\text{RMS})$	RMS on-state current (full sine wave)		$T_c = 125^\circ\text{C}$	25	A
$I_{\text{TSM}}$	Non repetitive surge peak on-state current (full cycle, $T_j$ initial = 25°C)	$F = 60 \text{ Hz}$	$t = 16.7 \text{ ms}$	260	A
		$F = 50 \text{ Hz}$	$t = 20 \text{ ms}$	250	
$I_t$	$I_t$ Value for fusing		$t_p = 10 \text{ ms}$	340	A s
$dl/dt$	Critical rate of rise of on-state current $I_G = 2 \times I_{\text{GT}}$ , $t_r \leq 100 \text{ ns}$	$F = 120 \text{ Hz}$	$T_j = 150^\circ\text{C}$	50	A/ $\mu\text{s}$
$V_{\text{DSM}}/V_{\text{RSM}}$	Non repetitive surge peak off-state voltage	$t_p = 10 \text{ ms}$	$T_j = 25^\circ\text{C}$	700	V
$I_{\text{GM}}$	Peak gate current	$t_p = 20 \mu\text{s}$	$T_j = 150^\circ\text{C}$	4	A
$P_{\text{G(AV)}}$	Average gate power dissipation		$T_j = 150^\circ\text{C}$	1	W
$T_{\text{stg}}$ $T_j$	Storage junction temperature range Operating junction temperature range			- 40 to + 150 - 40 to + 150	°C

## T2550H-600T

### ELECTRICAL CHARACTERISTICS ( $T_j = 25^\circ\text{C}$ , unless otherwise specified)

Symbol	Test Conditions	Quadrant		Value	Unit
$I_{GT}$ (1)	$V_D = 12 \text{ V}$ $R_L = 33 \Omega$	I - II - III	MAX.	50	mA
$V_{GT}$		I - II - III	MAX.	1.3	V
$V_{GD}$	$V_D = V_{DRM}$ $R_L = 3.3 \text{ k}\Omega$ $T_j = 150^\circ\text{C}$	I - II - III	MIN.	0.15	V
$I_H$ (2)	$I_T = 500 \text{ mA}$		MAX.	75	mA
$I_L$	$I_G = 1.2 I_{GT}$	I - II - III	MAX.	90	mA
$dV/dt$ (2)	$V_D = 67 \% V_{DRM}$ gate open $T_j = 150^\circ\text{C}$		MIN.	500	V/ $\mu\text{s}$
(dI/dt)c (2)	Without snubber $T_j = 150^\circ\text{C}$		MIN.	11.1	A/ms

### STATIC CHARACTERISTICS

Symbol	Test Conditions			Value	Unit
$V_{TM}$ (2)	$I_{TM} = 35 \text{ A}$	$t_p = 380 \mu\text{s}$	$T_j = 25^\circ\text{C}$	MAX.	V
$V_{to}$ (2)	Threshold voltage		$T_j = 150^\circ\text{C}$	MAX.	V
$R_d$ (2)	Dynamic resistance		$T_j = 150^\circ\text{C}$	MAX.	$\text{m}\Omega$
$I_{DRM}$	$V_{DRM} = V_{RRM}$		$T_j = 25^\circ\text{C}$	5	$\mu\text{A}$
			$T_j = 150^\circ\text{C}$	8.5	mA
	$V_{DRM} / V_{RRM} = 400 \text{ V}$ (at mains peak voltage)		$T_j = 150^\circ\text{C}$	5.5	

Note 1: minimum  $I_{GT}$  is guaranteed at 10% of  $I_{GT}$  max.

Note 2: for both polarities of A2 referenced to A1

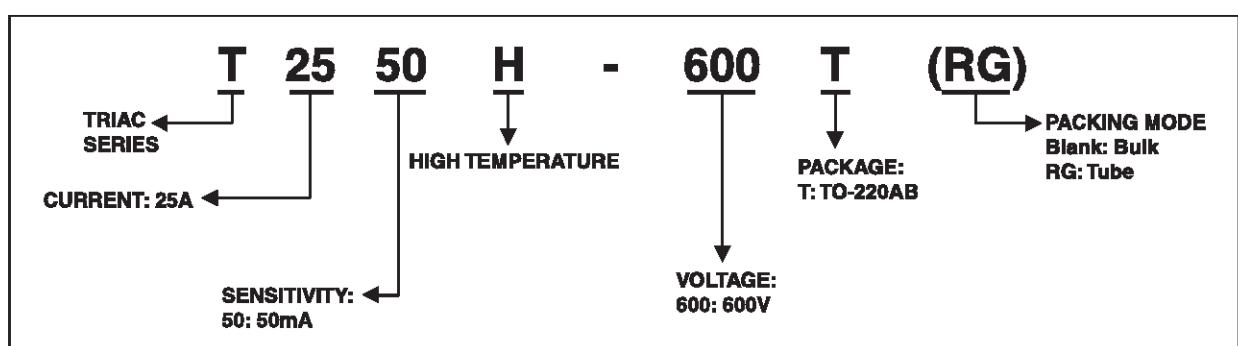
### THERMAL RESISTANCE

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	Junction to case (AC)	0.8	$^\circ\text{C/W}$

### PRODUCT SELECTOR

Part Number	Voltage	Sensitivity	Type	Package
T2550H-600T	600 V	50 mA	Snubberless	TO-220AB

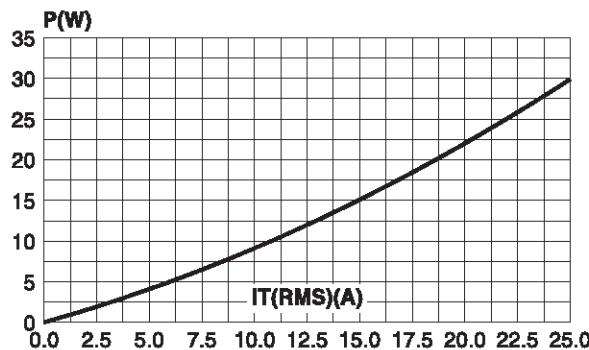
### ORDERING INFORMATION



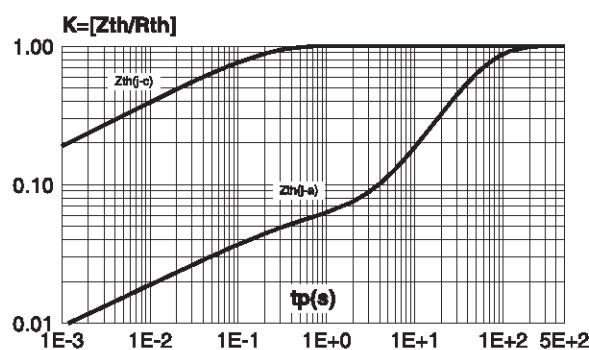
## OTHER INFORMATION

Part Number	Marking	Weight	Base quantity	Packing mode
T2550H-600T	T2550H600T	2.3 g	250	Bulk
T2550H-600TRG	T2550H600T	2.3 g	50	Tube

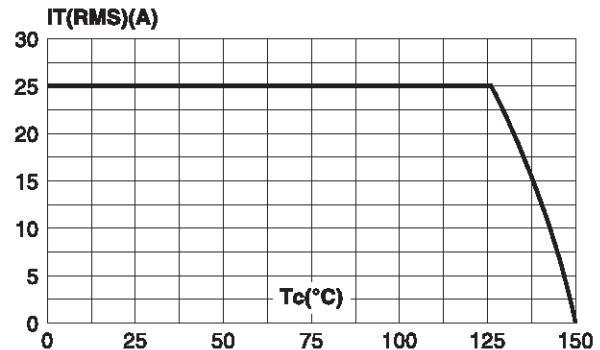
**Fig. 1:** Maximum power dissipation versus RMS on-state current (full cycle).



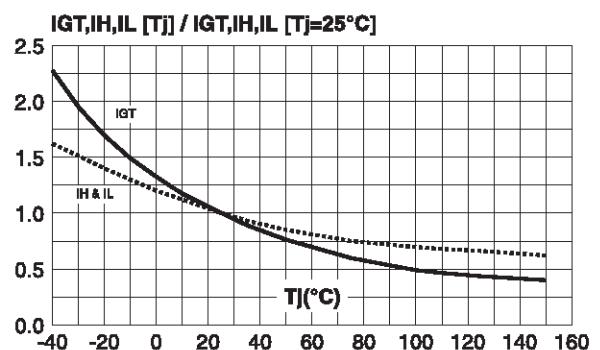
**Fig. 3:** Relative variation of thermal impedance versus pulse duration.



**Fig. 2:** RMS on-state current versus case temperature (full cycle).

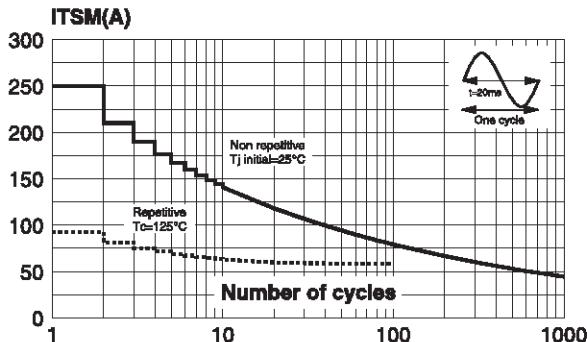


**Fig. 4:** Relative variation of gate trigger current, holding current and latching current versus junction temperature (typical values).

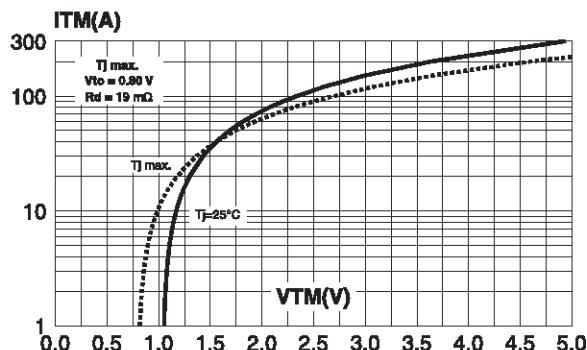


## T2550H-600T

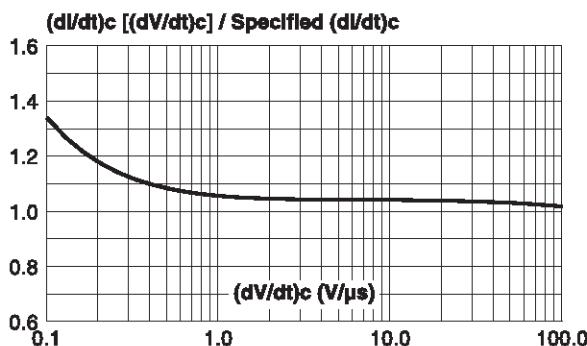
**Fig. 5:** Surge peak on-state current versus number of cycles.



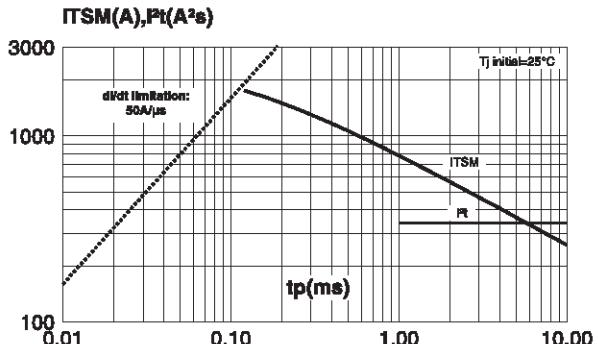
**Fig. 7:** On-state characteristics (maximum values).



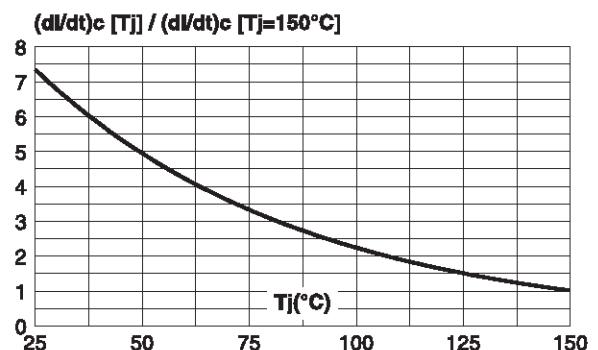
**Fig. 9:** Relative variation of critical rate of decrease of main current versus  $(dV/dt)_c$  (typical values).



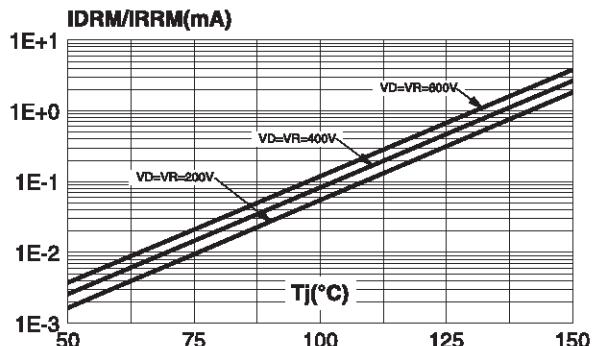
**Fig. 6:** Non-repetitive surge peak on-state current for a sinusoidal pulse with width  $t_p < 10\text{ms}$ , and corresponding value of  $I_t$ .



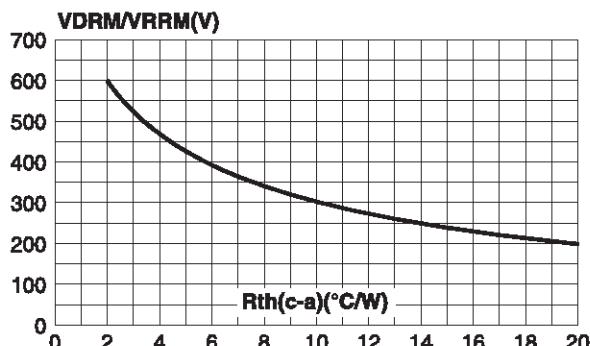
**Fig. 8:** Relative variation of critical rate of decrease of main current versus junction temperature (typical values).



**Fig. 10:** Leakage current versus junction temperature for different values of blocking voltage (typical values).



**Fig. 11:** Acceptable repetitive peak off-state voltage versus case-ambient thermal resistance.



## PACKAGE MECHANICAL DATA

TO-220AB (Plastic)

The mechanical drawing shows two views of the TO-220AB package. The left view is a top-down cross-section showing lead thicknesses b1, b2, b3, and b4; lead spacing l1, l2, l3; lead height h; lead pitch p; and lead width w. The right view is a side profile showing lead height h, lead width w, lead thickness c1, lead spacing c2, lead pitch c3, and lead width c4. Dimensions are labeled as follows:

- A: 15.20
- a1: 3.75
- a2: 13.00
- B: 10.00
- b1: 0.61
- b2: 1.23
- C: 4.40
- c1: 0.49
- c2: 2.40
- e: 2.40
- F: 6.20
- h: 3.75
- I: 3.75
- I4: 15.80
- L: 2.65
- l1: 1.14
- l2: 1.14
- l3: 1.14
- M: 2.60
- p: 5.00
- w: 1.20

**DIMENSIONS**

REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	15.20		15.90	0.598		0.625
a1		3.75			0.147	
a2	13.00		14.00	0.511		0.551
B	10.00		10.40	0.393		0.409
b1	0.61		0.88	0.024		0.034
b2	1.23		1.32	0.048		0.051
C	4.40		4.60	0.173		0.181
c1	0.49		0.70	0.019		0.027
c2	2.40		2.72	0.094		0.107
e	2.40		2.70	0.094		0.106
F	6.20		6.60	0.244		0.259
I	3.75		3.85	0.147		0.151
I4	15.80	16.40	16.80	0.622	0.646	0.661
L	2.65		2.95	0.104		0.116
l1	1.14		1.70	0.044		0.066
l2	1.14		1.70	0.044		0.066
l3	1.14		1.70	0.044		0.066
M		2.60			0.102	

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